

**High Speed Switching Diode****Forward Current - 400 mA**
Reverse Voltage - 250 V**Description**



- Power Dissipation of 250mW
- Fast Switching Device (TRR<50nS)
- High Stability and High Reliability
- Low Reverse Leakage

Mechanical Data

- Case: SOD323 Package
- Case Material: "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Terminals: Matte tin plated, solderable per MIL-STD-750, method 2026

- Component in accordance to RoHS

- Halogen Free

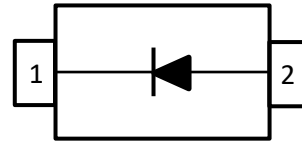
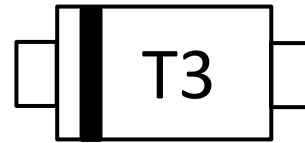
Note: Products with logo  or  are made by HY Electronic (Cayman) Limited.

Ordering Information

- Package :SOD323
- Reel Size :7 (inches)
- Quantity Per Reel :3,000/Tape & Reel
- Quantity One Box :45,000/Tape & Reel

Package Outline

SOD323 Top View

Device Schematic & PIN Configuration**Product Type Marking Code**

"T3" = Product Type Marking Code

Maximum Ratings (@TA = +25°C, unless otherwise specified.)**Absolute Ratings**

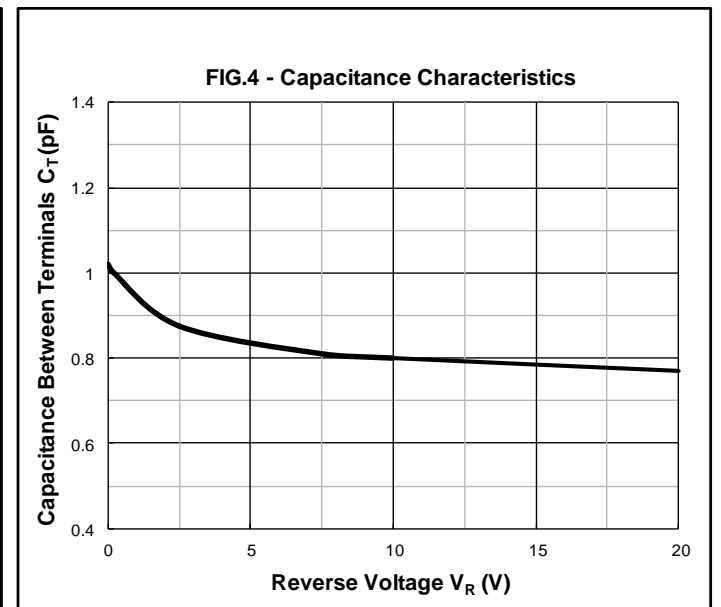
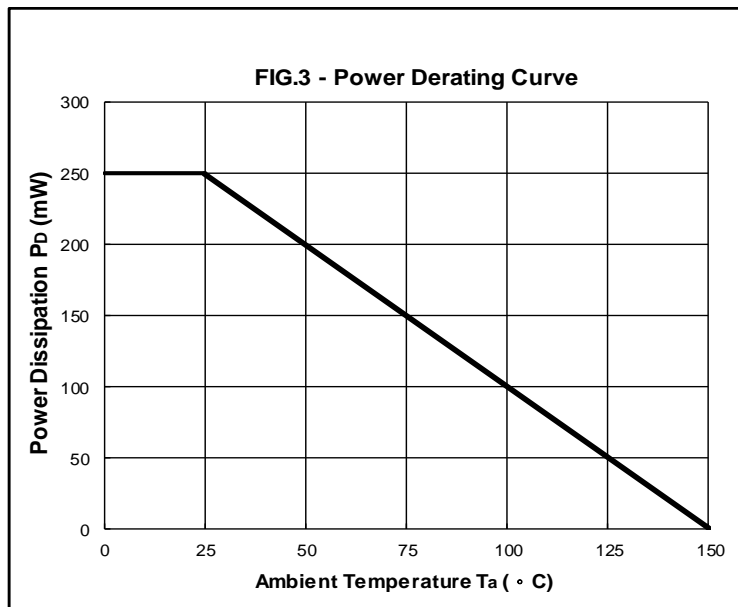
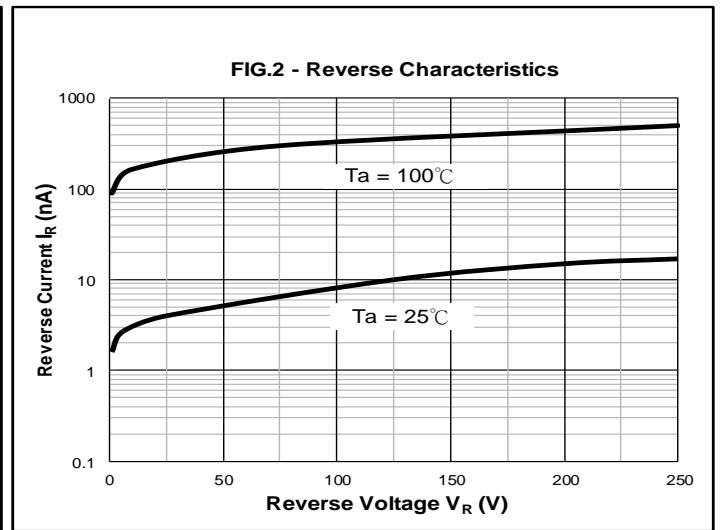
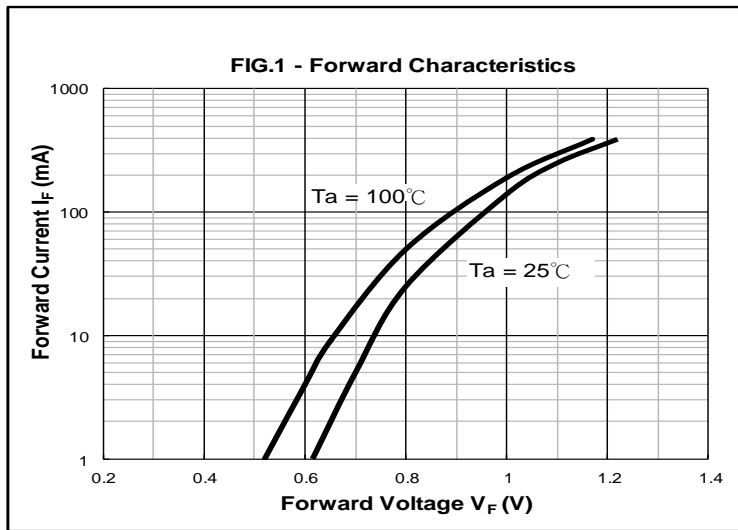
Parameter	Symbol	Value	Unit
Repetitive Peak Reverse Voltage	V_R	250	V
Working Inverse Voltage	W_{IV}	75	V
Average Rectified Current	I_o	200	mA
Forward Rectified Current	I_{FM}	400	mA
Peak Forward Surge Current @ $t_p = 1\text{ms}$	I_{FSM}	1.7	A
Power Dissipation	P_D	250	mW
Junction Temperature	T_J	150	°C
Storage Temperature Range	T_{STG}	-65 to +150	°C
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	500	°C/W

Electrical Characteristics

Parameter	Test Conditions	Symbol	Min	Typ	Max	Unit
Reverse Voltage	$I_R=100\mu\text{A}$	V_{BR}	250	-	-	V
Reverse Current	$V_R=200\text{V}$	I_R	-	-	0.1	μA
Forward Voltage	$I_F=100\text{mA}$	V_F	-	-	1.00	V
	$I_F=200\text{mA}$		-	-	1.25	
Reverse Recovery Time	$I_F=I_R=30\text{mA}, I_{rr}=3\text{mA}, R_L=100\Omega$	T_{RR}	-	-	50	ns
Junction Capacitance	$V_R = 0\text{V}, F = 1\text{MHz}$	C_D	-	-	5	pF

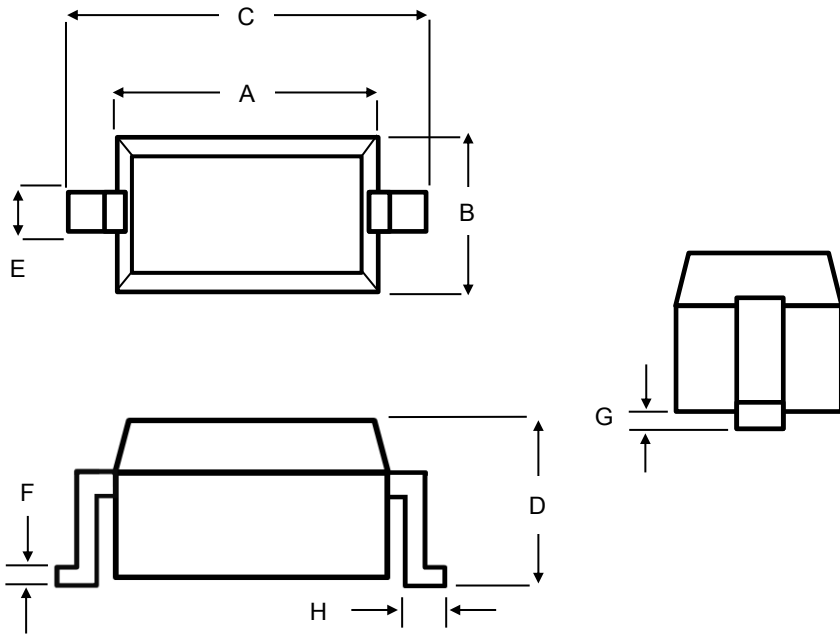


Rating and Characteristic Curves



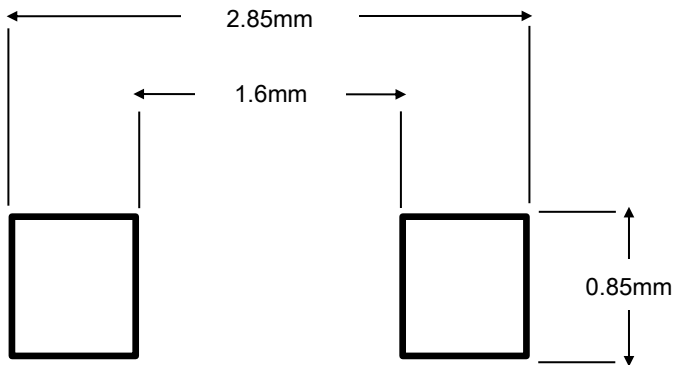


Package Outline Dimensions



SOD323 Package		
Dim	Min	Max
A	1.6	1.8
B	1.2	1.4
C	2.5	2.7
D	-	1.0
E	0.25	0.35
F	0.08	0.15
G	-	0.1
H	0.25	0.4
All Dimensions in mm		

Suggested Soldering Pad Layout



Note:

- 1.The pad layout is for reference purposes only.
- 2.General tolerance $\pm 0.05\text{mm}$



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